

### • Product Summary

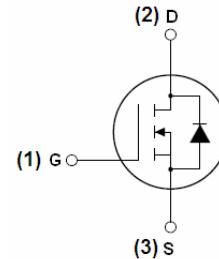
Part #	V <sub>DS</sub>	R <sub>DS(on).typ</sub> (@V <sub>GS</sub> =10V)	R <sub>DS(on).typ</sub> (@V <sub>GS</sub> =4.5V)	I <sub>D</sub>
EFM050N03D	30V	5mΩ	6.5mΩ	80A

### • Description

- The EFM050N03D is the high cell density trenched
- N-ch MOSFETs which provide excellent
- RDSON and gate charge for most of the
- synchronous buck converter applications.
- The EFM050N03D meet the RoHS and Green
- Product requirement, 100 % EAS guaranteed
- with full function reliability approved.

### • Application

- Super Low Gate Charge 100% EAS Guaranteed
- Green Device Available Excellent CdV/dt effect decline
- Advanced high cell density Trench technology


**N-Channel MOSFET**

**TO-252-2L**

### • Ordering Information:

Part NO.	EFM050N03D
Marking	050N03D****
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

### • Absolute Maximum Ratings (T<sub>C</sub>=25°C)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	80	A
Drain Current-Pulsed <sup>(Note 1)</sup>	I <sub>DM</sub>	170	A
Maximum Power Dissipation	P <sub>D</sub>	80	W
Single pulse avalanche energy <sup>(Note 5)</sup>	E <sub>AS</sub>	306	mJ
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 To 150	°C

### • Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	R <sub>θJC</sub>	1.8	°C/W
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**• Static Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise stated)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V} I_{\text{D}}=250\mu\text{A}$	30	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=30\text{V} V_{\text{GS}}=0\text{V}$	--	--	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V} V_{\text{DS}}=0\text{V}$	--	--	$\pm 100$	nA
<b>On Characteristics</b> <small>(Note 3)</small>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}} I_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.5	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V} I_{\text{D}}=30\text{A}$	--	5	6	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V} I_{\text{D}}=24\text{A}$	--	6.5	9	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V} I_{\text{D}}=24\text{A}$	20	--	--	S

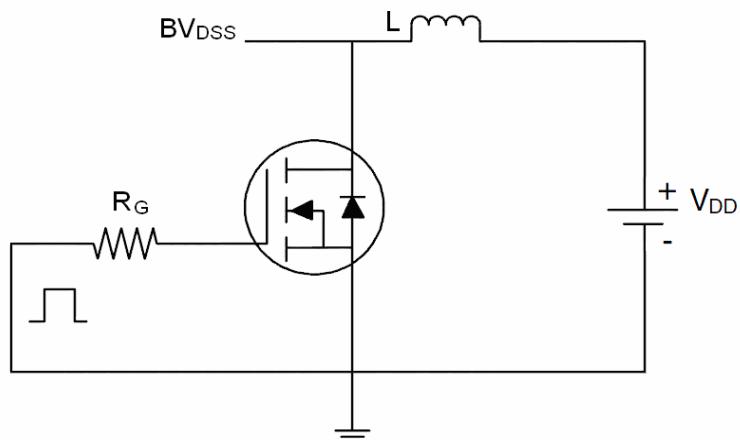
<b>Dynamic Characteristics</b> <small>(Note 4)</small>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=15\text{V} V_{\text{GS}}=0\text{V}$ $F=1.0\text{MHz}$	--	2330	--	PF
Output Capacitance	$C_{\text{oss}}$		--	460	--	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	230	--	PF
<b>Switching Characteristics</b> <small>(Note 4)</small>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=10\text{V} I_{\text{D}}=30\text{A}$ $V_{\text{GS}}=10\text{V} R_{\text{G}}=2.7\Omega$	--	20	--	nS
Turn-on Rise Time	$t_{\text{r}}$		--	15	--	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		--	60	--	nS
Turn-Off Fall Time	$t_{\text{f}}$		--	10	--	nS
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{DS}}=10\text{V} I_{\text{D}}=30\text{A}$ $V_{\text{GS}}=10\text{V}$	--	51	--	nC
Gate-Source Charge	$Q_{\text{gs}}$		--	14	--	nC
Gate-Drain Charge	$Q_{\text{gd}}$		--	11	--	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <small>(Note 3)</small>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V} I_{\text{s}}=30\text{A}$	--	--	1.2	V
Diode Forward Current <small>(Note 2)</small>	$I_{\text{s}}$		--	--	80	A

**Notes:**

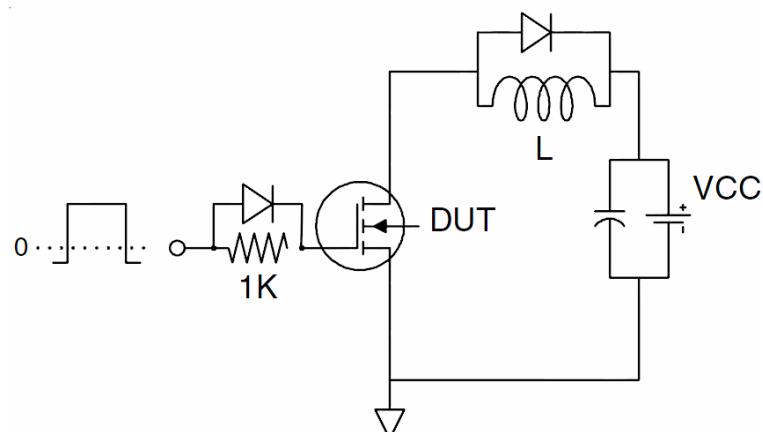
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS condition:  $T_J=25^\circ\text{C}, V_{\text{DD}}=15\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_{\text{g}}=25\Omega$

• Test circuit

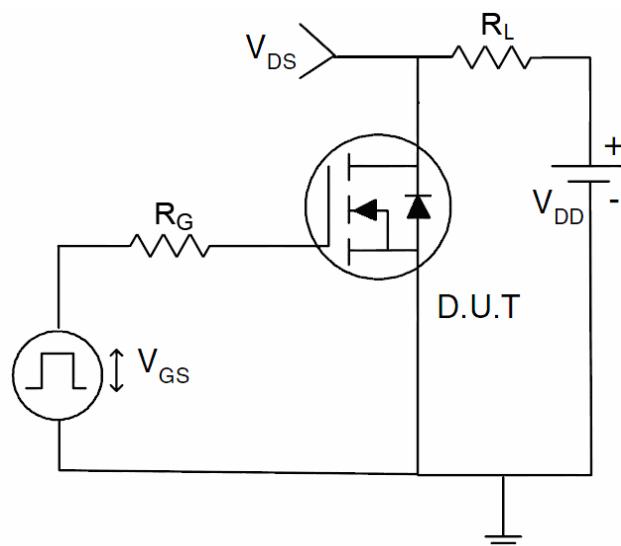
**1) E<sub>AS</sub> Test Circuits**



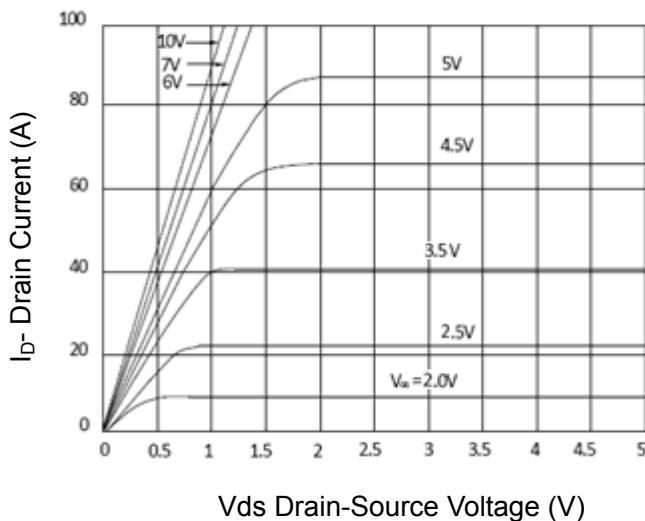
**2) Gate Charge Test Circuit:**



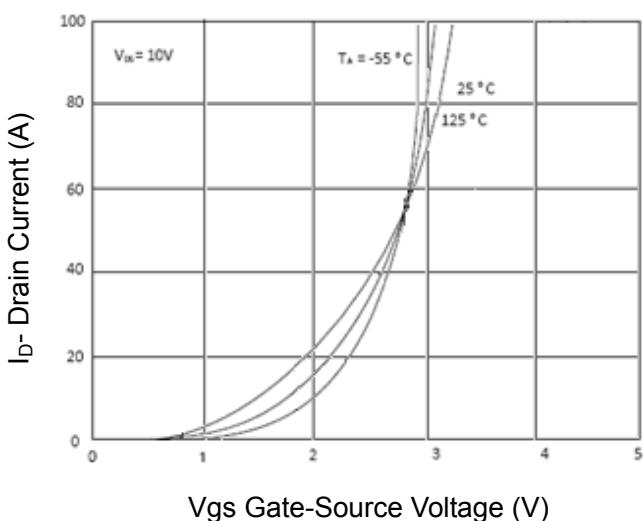
**3) Switch Time Test Circuit:**



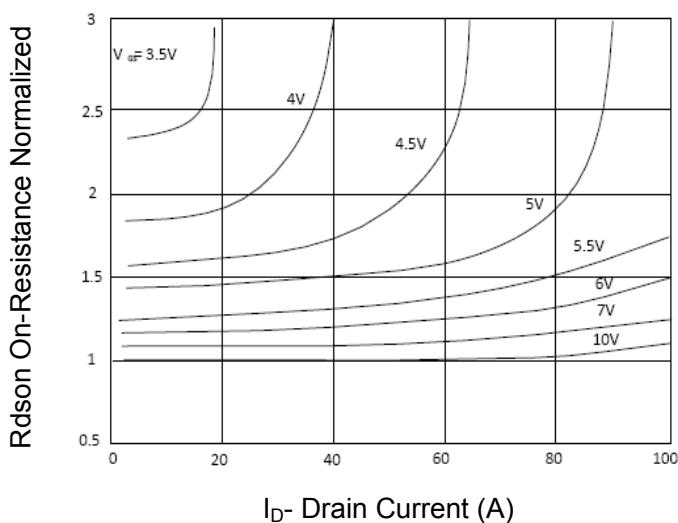
## • Typical Characteristics



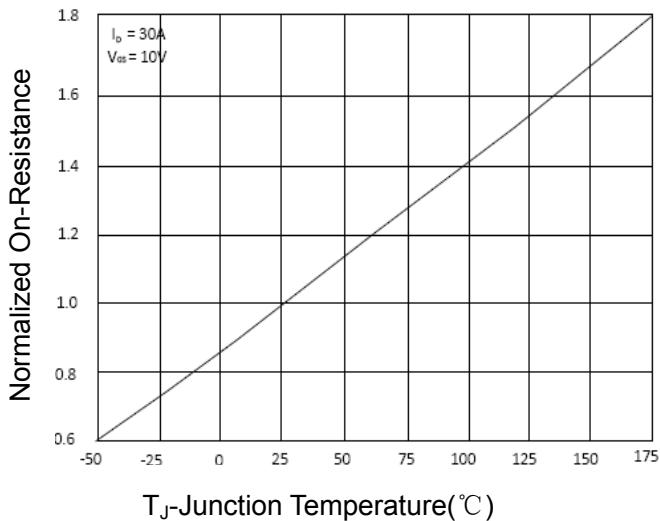
**Figure 1 Output Characteristics**



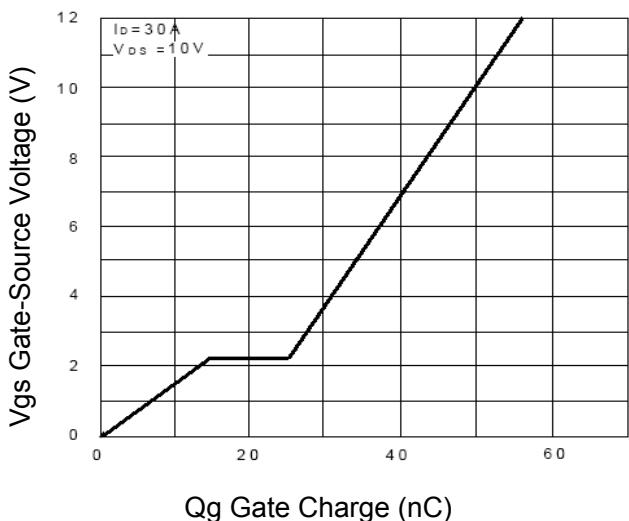
**Figure 2 Transfer Characteristics**



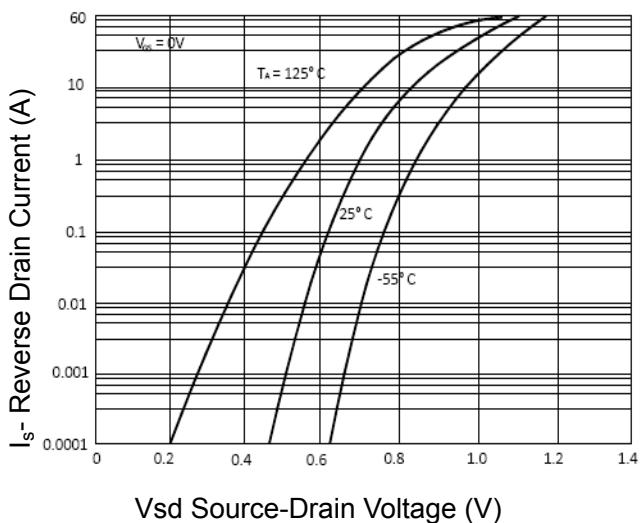
**Figure 3 Rdson- Drain Current**



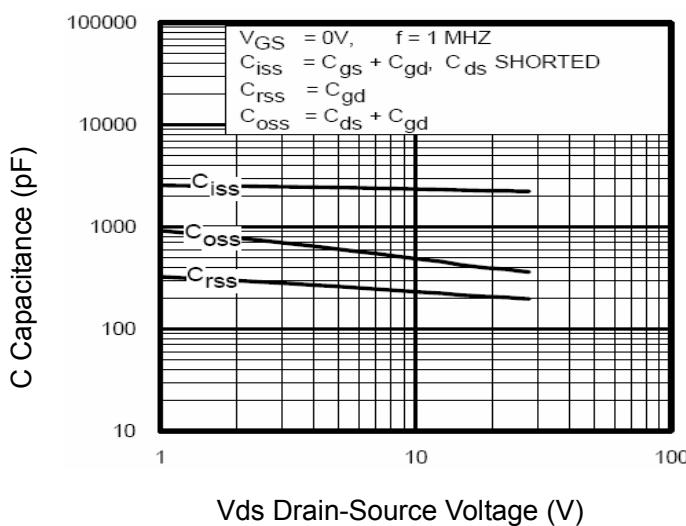
**Figure 4 Rdson-Junction Temperature**



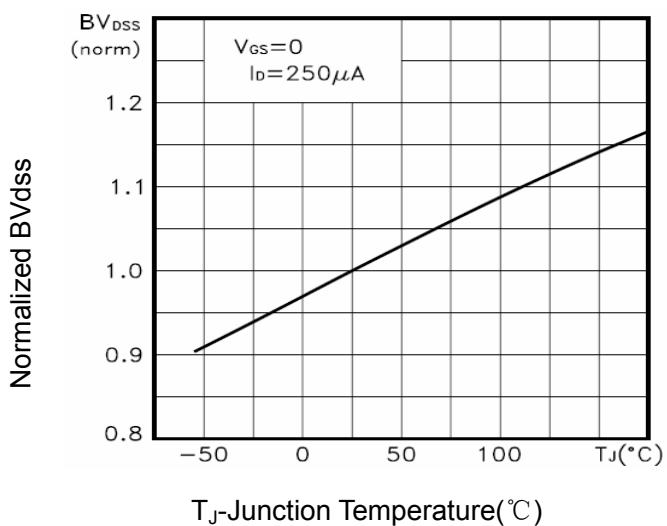
**Figure 5 Gate Charge**



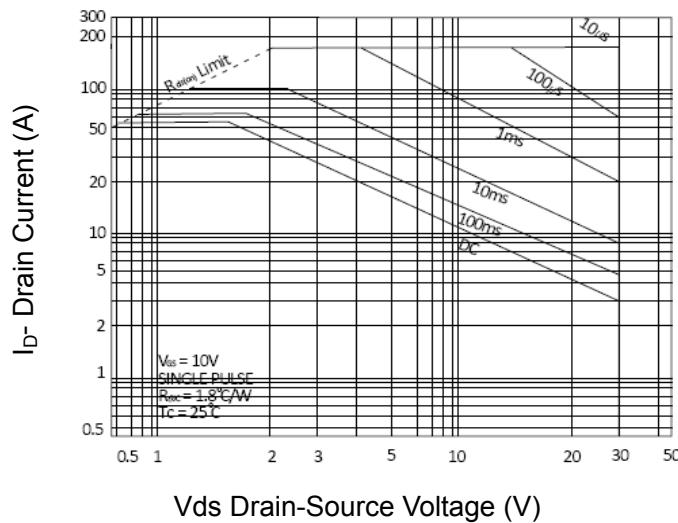
**Figure 6 Source- Drain Diode Forward**



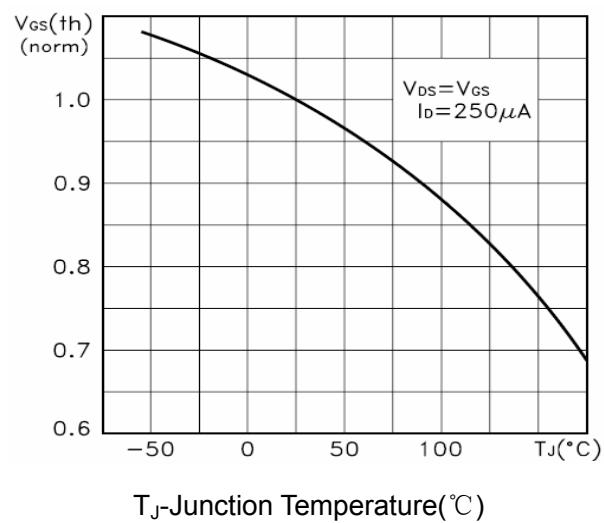
**Figure 7 Capacitance vs Vds**



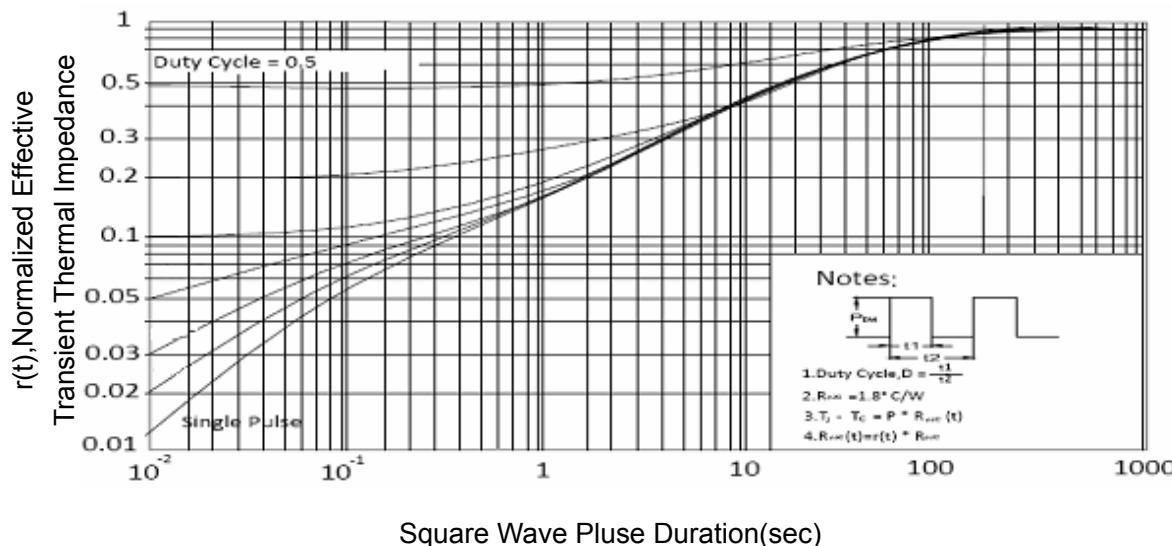
**Figure 9  $\text{BV}_{\text{dss}}$  vs Junction Temperature**



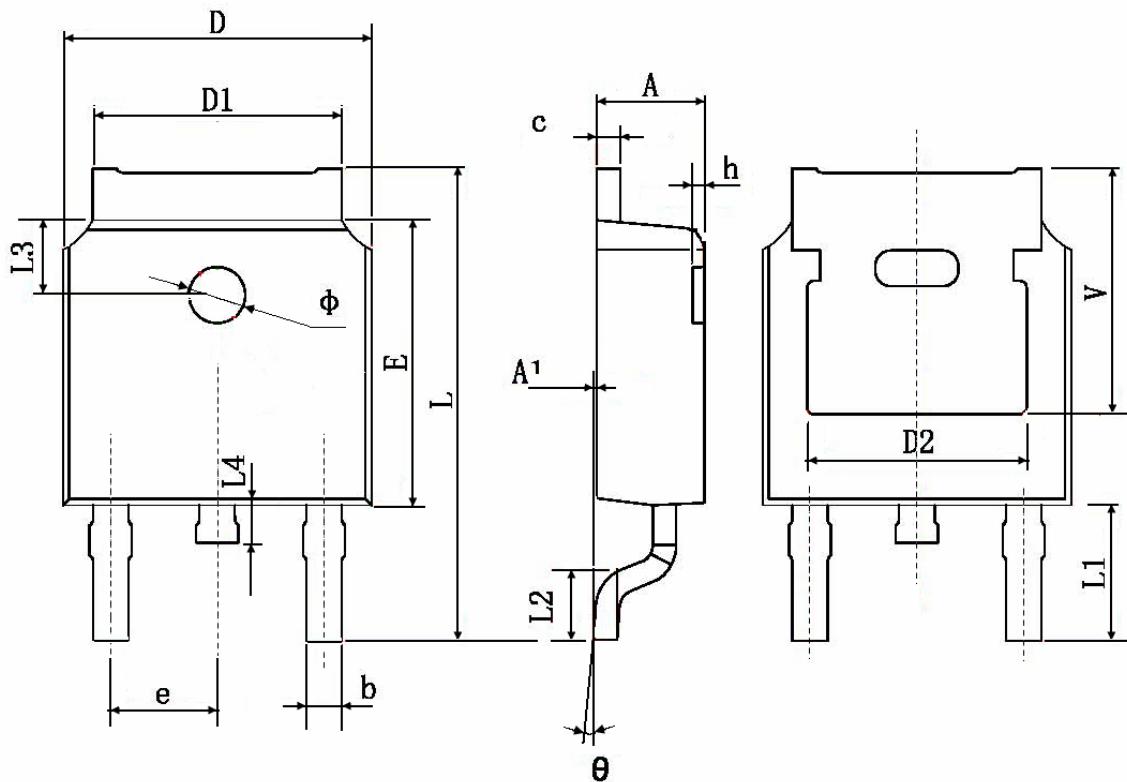
**Figure 8 Safe Operation Area**



**Figure 10  $V_{GS(\text{th})}$  vs Junction Temperature**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

**TO-252 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.83 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	